



Material Content Data Sheet



Sales Product Name		TLE8203E		Issued		27. September 2017		
MA#		MA001172520						
Package		PG-DSO-36-50		Weight*		609.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.642	1.42	1.42	14172	14172
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		93	
	non noble metal	zinc	7440-66-6	0.227	0.04		373	
	non noble metal	iron	7439-89-6	4.546	0.75		7454	
wire	non noble metal	copper	7440-50-8	184.568	30.27	31.07	302664	310584
	noble metal	gold	7440-57-5	2.936	0.48	0.48	4814	4814
	encapsulation	organic material	carbon black	1333-86-4	0.801	0.13		1313
encapsulation	plastics	epoxy resin	-	36.825	6.04		60388	
	inorganic material	silicondioxide	60676-86-0	362.648	59.45	65.62	594688	656389
leadfinish	non noble metal	tin	7440-31-5	5.440	0.89	0.89	8921	8921
plating	noble metal	silver	7440-22-4	0.791	0.13	0.13	1297	1297
glue	plastics	epoxy resin	-	0.583	0.10		956	
	noble metal	silver	7440-22-4	1.748	0.29	0.39	2867	3823
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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